

SDRAM의 모든것



SDRAM의 기초 원리

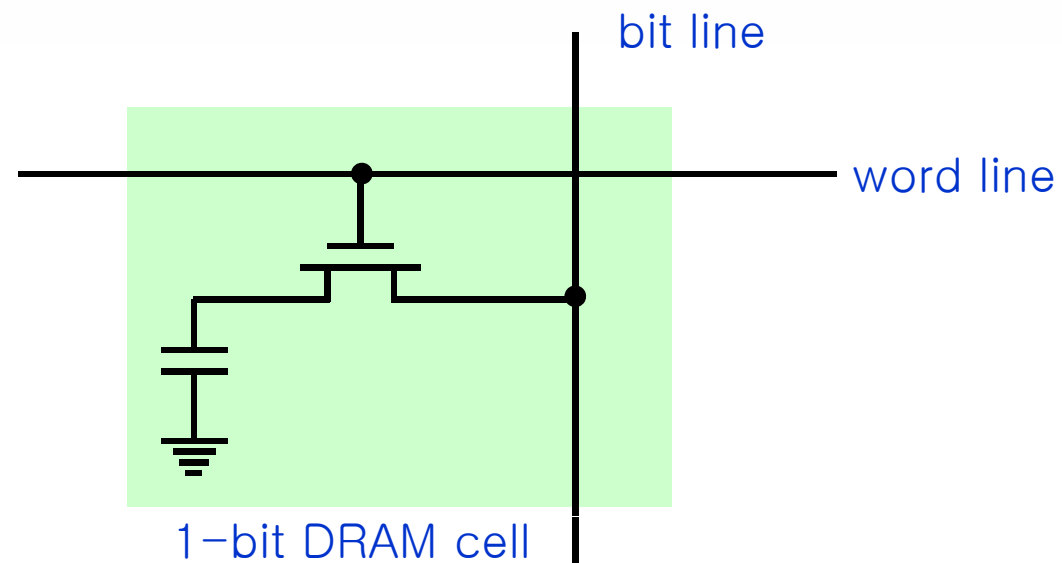
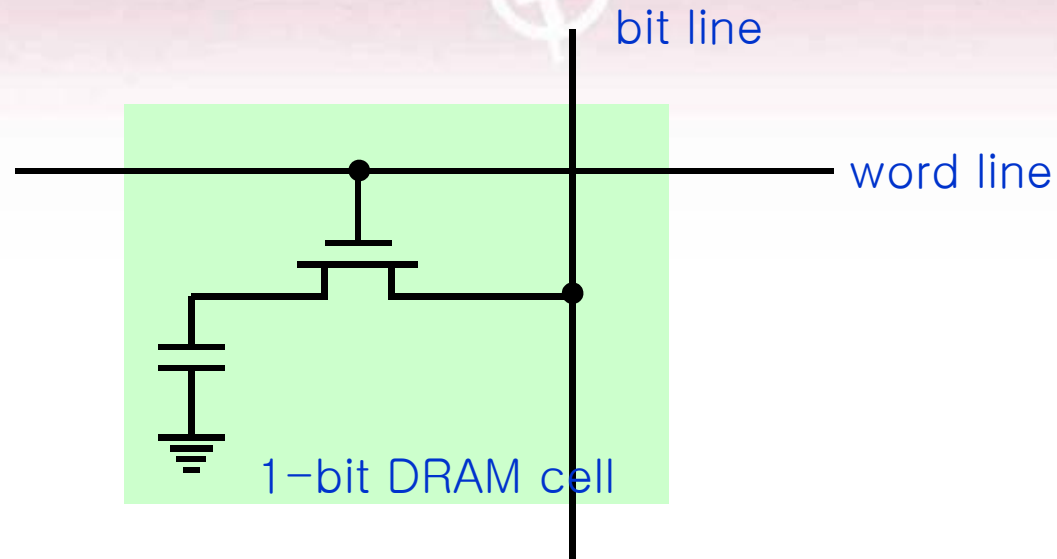


그림. Dynamic Memory Cell

SDRAM의 기초 원리

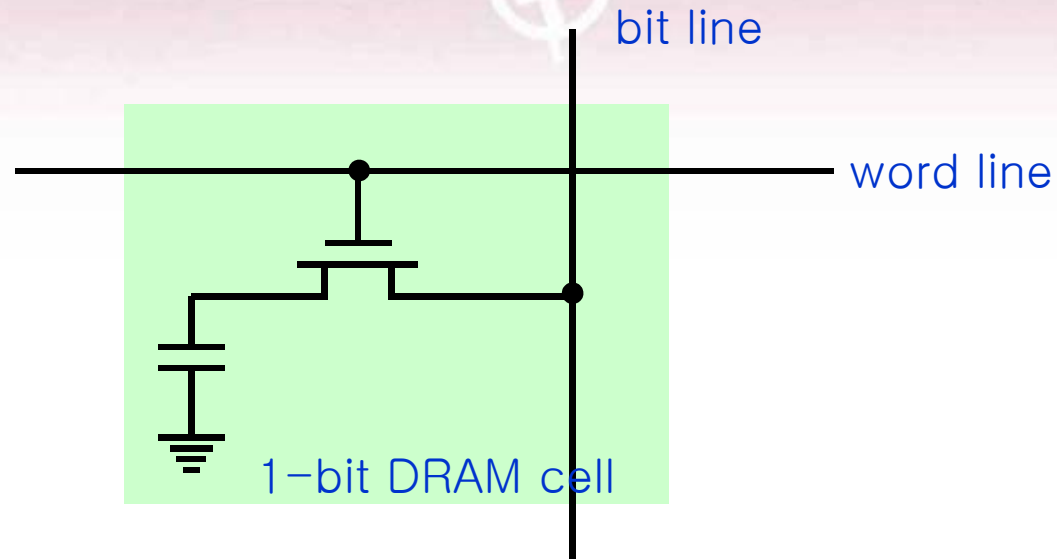


To store a **1** in this cell, a **HIGH** voltage is placed on the bit line, causing the capacitor to charge through the on transistor.

그림. Writing 1 in a Dynamic Memories



SDRAM의 기초 원리

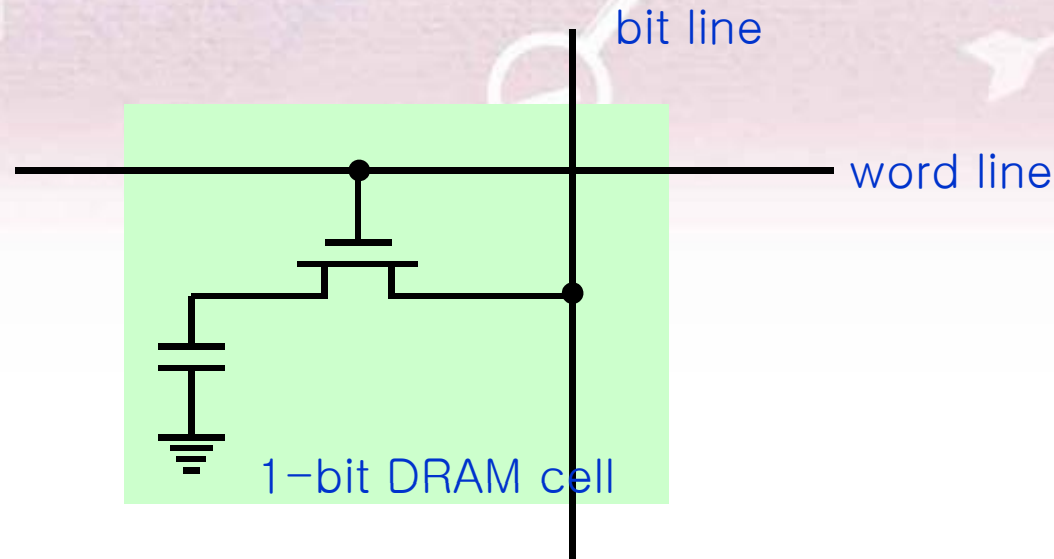


To store a 0 in this cell, a LOW voltage is placed on the bit line, causing the capacitor to discharge through the on transistor.

그림. Writing 0 in a Dynamic Memories



SDRAM의 기초 원리

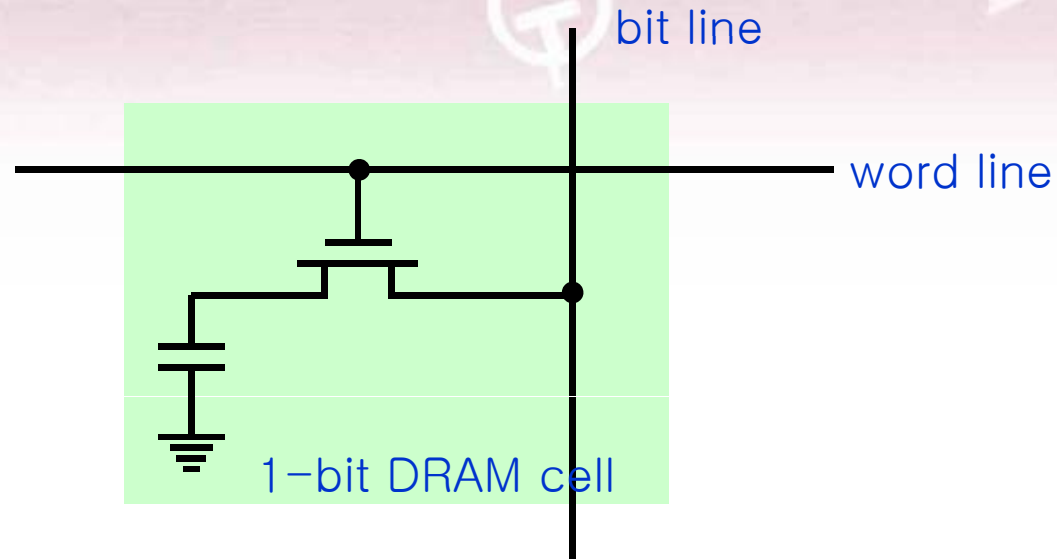


To read the DRAM cell, the bit line is precharged to a voltage **halfway between HIGH and LOW**, and then the word line is set HIGH. Depending on the charge in the capacitor, the precharged bit line is pulled slightly higher or lower. A **sense amplifier** detects this small change and recovers a 1 or a 0.

그림. Destructive Reads



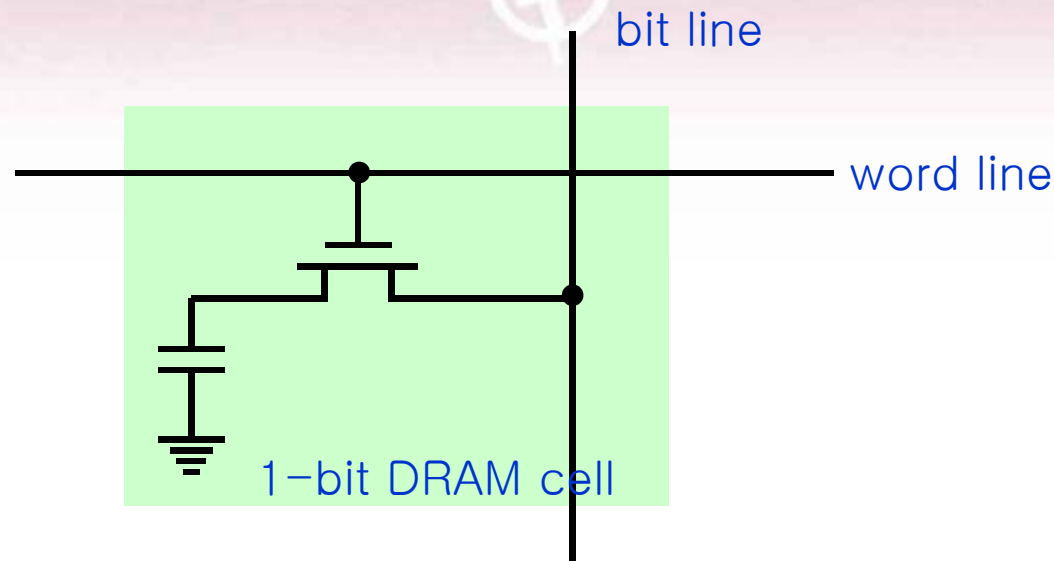
SDRAM의 기초 원리



The read operation discharges the capacitor.
Therefore a read operation in a dynamic memory must be **immediately followed by a write** operation **of the same value read** to restore the capacitor charges.

그림. Recovering from Destructive Reads

SDRAM의 기초 원리

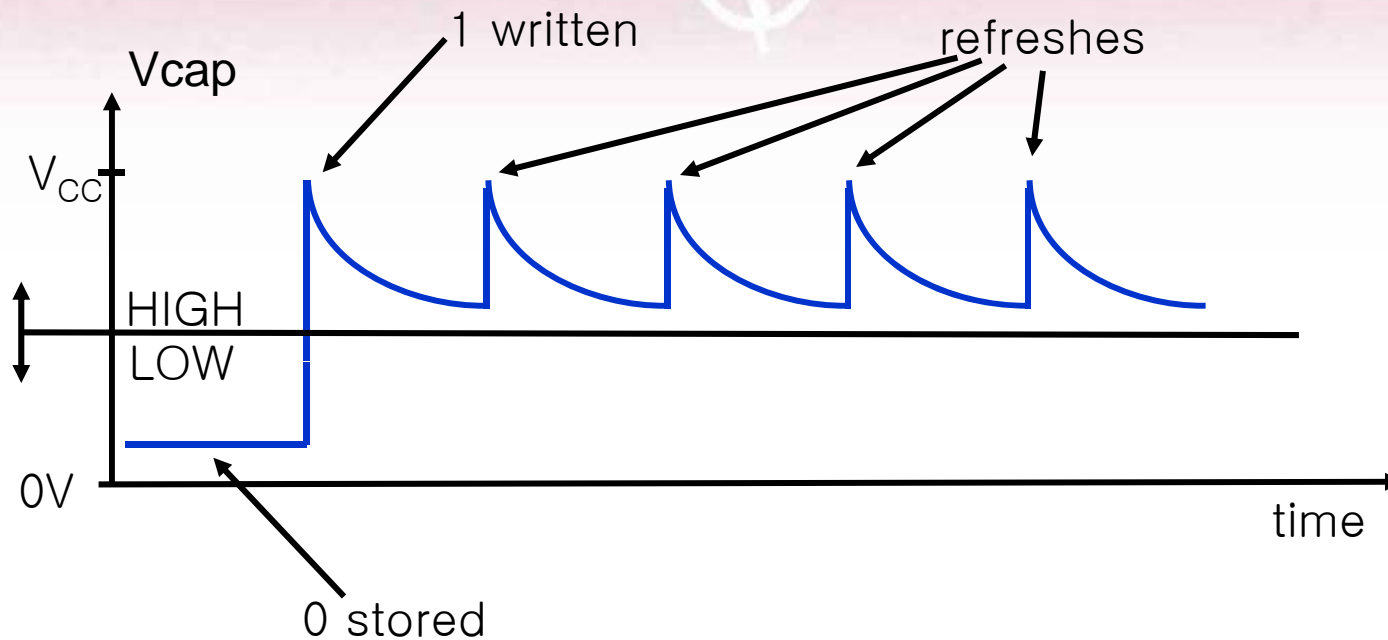


The problem with this cell is that it is not bi-stable: **only the state 0 can be kept indefinitely**, when the cell is in state 1, the charge stored in the capacitor **slowly dissipates** and the **data is lost**.

그림. Forgetful Memories



SDRAM의 기초 원리



The solution is to **periodically refresh** the memory cells by reading and writing back each one of them.

그림. Refreshing the Memory

SDRAM CONTROLLER

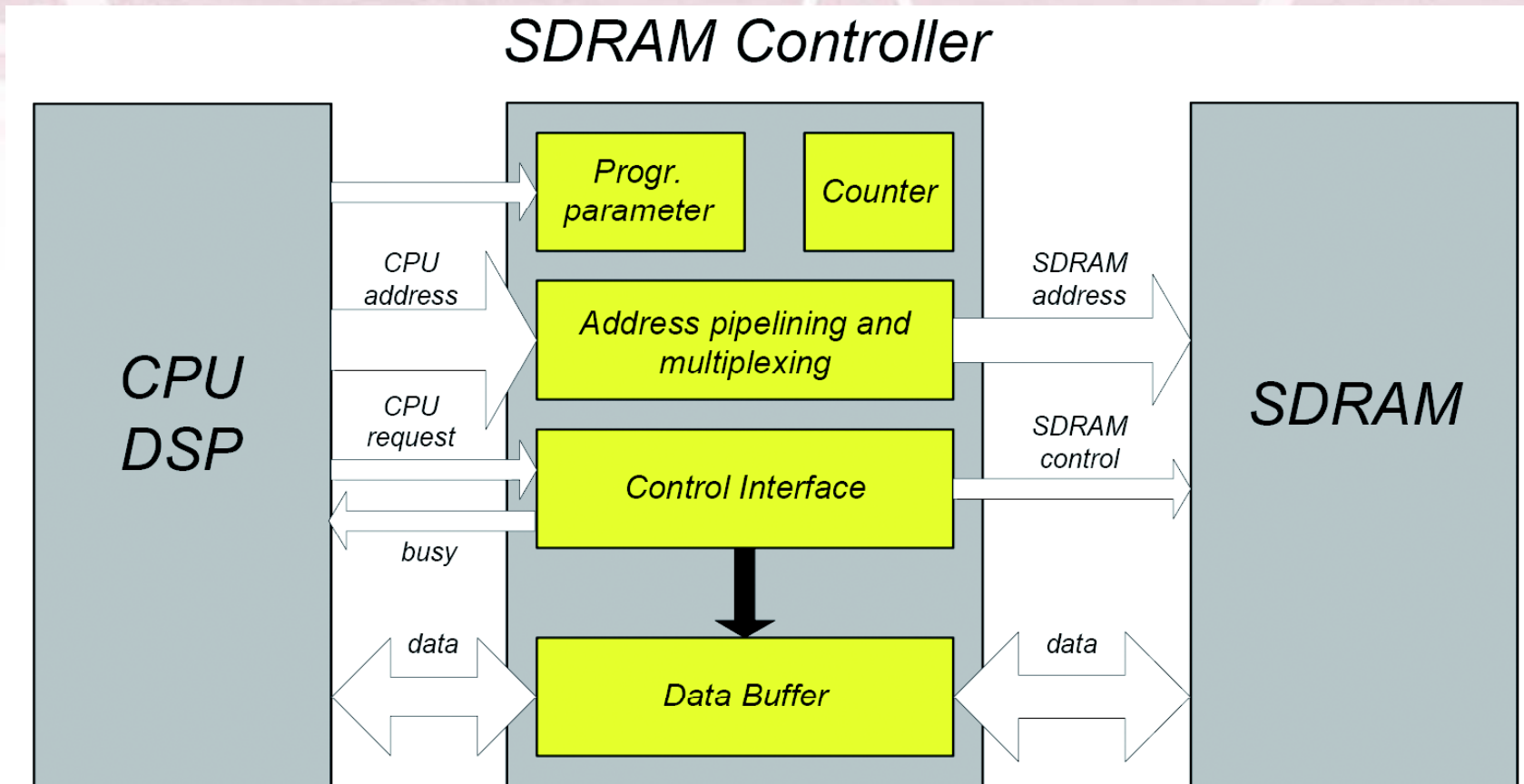


그림. Host Interface of SDRAM

x4, x8, x16

Vcc	Vcc	Vcc	1	54	Vss	Vss	Vss
DQ0	DQ0	NC	2	53	NC	DQ7	DQ15
VccQ	VccQ	VccQ	3	52	VssQ	VssQ	VssQ
DQ1	NC	NC	4	51	NC	NC	DQ14
DQ2	DQ1	DQ0	5	50	DQ3	DQ6	DQ13
VssQ	VssQ	VssQ	6	49	VccQ	VccQ	VccQ
DQ3	NC	NC	7	48	NC	NC	DQ12
DQ4	DQ2	NC	8	47	NC	DQ5	DQ11
VccQ	VccQ	VccQ	9	46	VssQ	VssQ	VssQ
DQ5	NC	NC	10	45	NC	NC	DQ10
DQ6	DQ3	DQ1	11	44	DQ2	DQ4	DQ9
VssQ	VssQ	VssQ	12	43	VccQ	VccQ	VccQ
DQ7	NC	NC	13	42	NC	NC	DQ8
Vcc	Vcc	Vcc	14	41	Vss	Vss	Vss
LDQM	NC	NC	15	40	NC	NC	NC
/WE	/WE	/WE	16	39	DQM	DQM	UDQM
/CAS	/CAS	/CAS	17	38	CLK	CLK	CLK
/RAS	/RAS	/RAS	18	37	CKE	CKE	CKE
/CS	/CS	/CS	19	36	NC	NC	NC
A13	A13	A13	20	35	A11	A11	A11
A12	A12	A12	21	34	A9	A9	A9
A10	A10	A10	22	33	A8	A8	A8
A0	A0	A0	23	32	A7	A7	A7
A1	A1	A1	24	31	A6	A6	A6
A2	A2	A2	25	30	A5	A5	A5
A3	A3	A3	26	29	A4	A4	A4
Vcc	Vcc	Vcc	27	28	Vss	Vss	Vc

x4 (64M / 128M)

x8 (64M / 128M)

x16 (64M / 128M)

그림. Pin configuration of 64M/128M SDRAM



SDRAM의 내부 구조

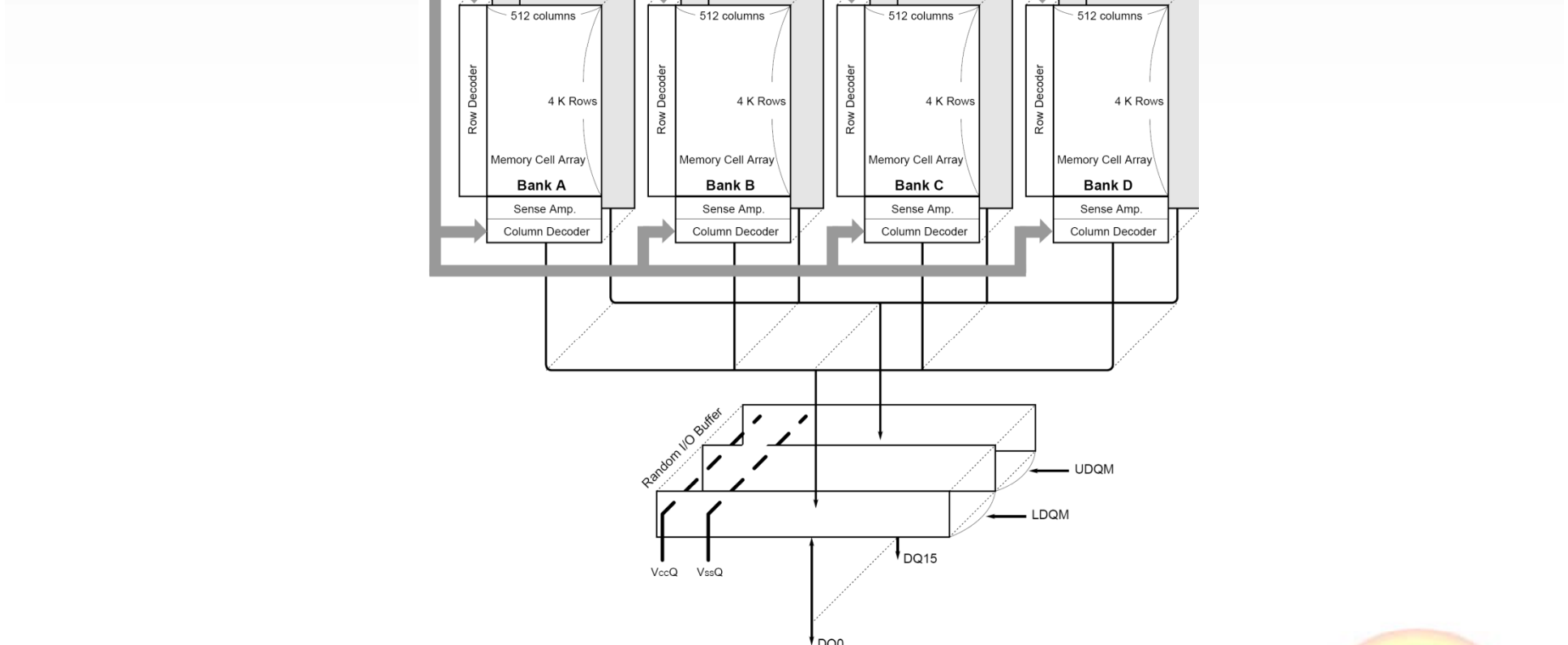


그림. Block diagram of 128M SDRAM

BANK

Bank 3	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0	
	1	1	1	1	1	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	F8000
	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	FFFFF
Bank 2	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0	
	1	1	1	1	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	F0000
	1	1	1	1	0	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	F7FFF
Bank 1	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0	
	1	1	1	0	1	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	E8000
	1	1	1	0	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	FFFFF
Bank 0	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0	
	1	1	1	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	E0000
	1	1	1	0	0	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	E7FFF

그림. BANK assignment rule



ADDRESS DECODING for SDRAM

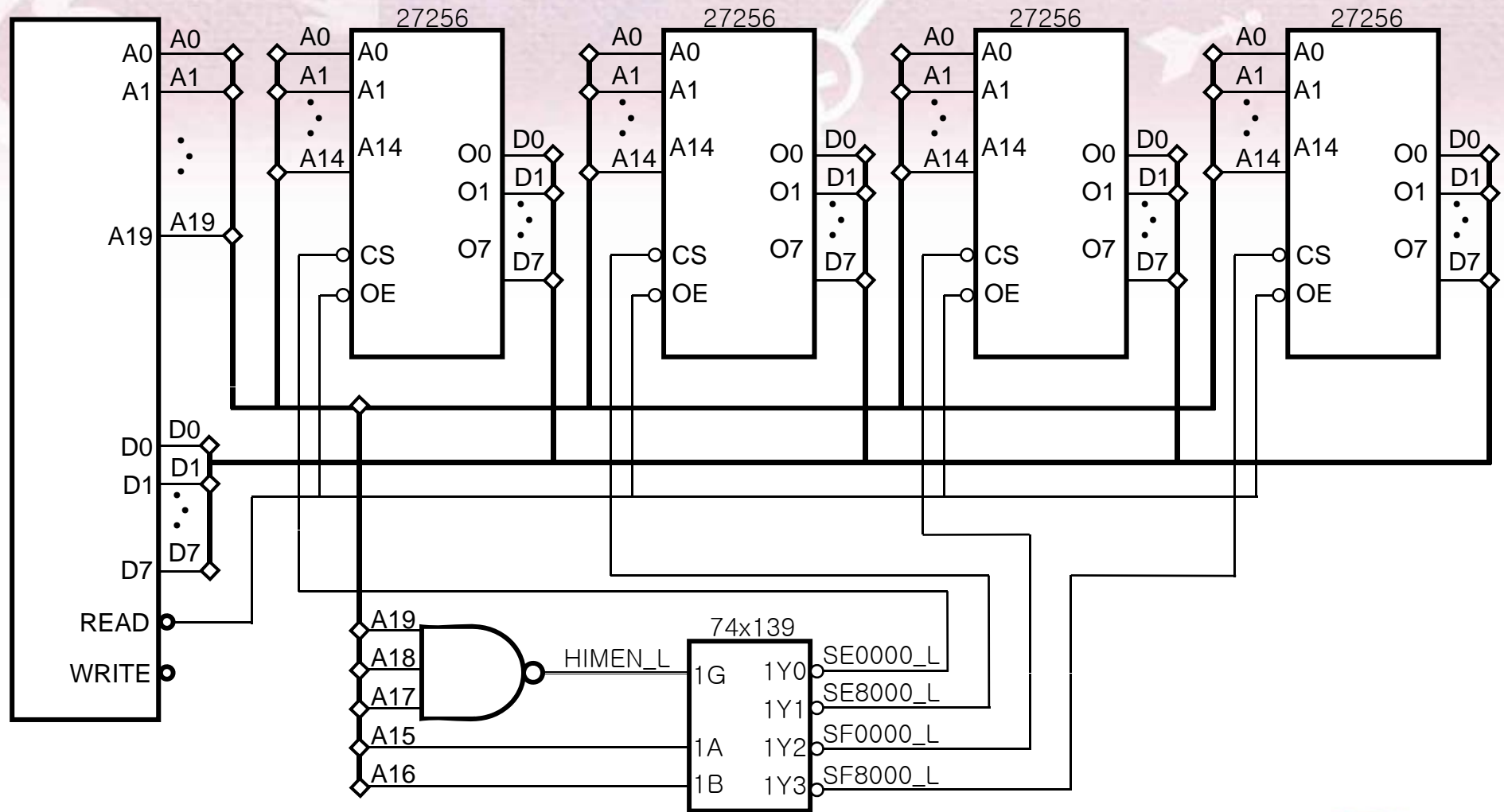
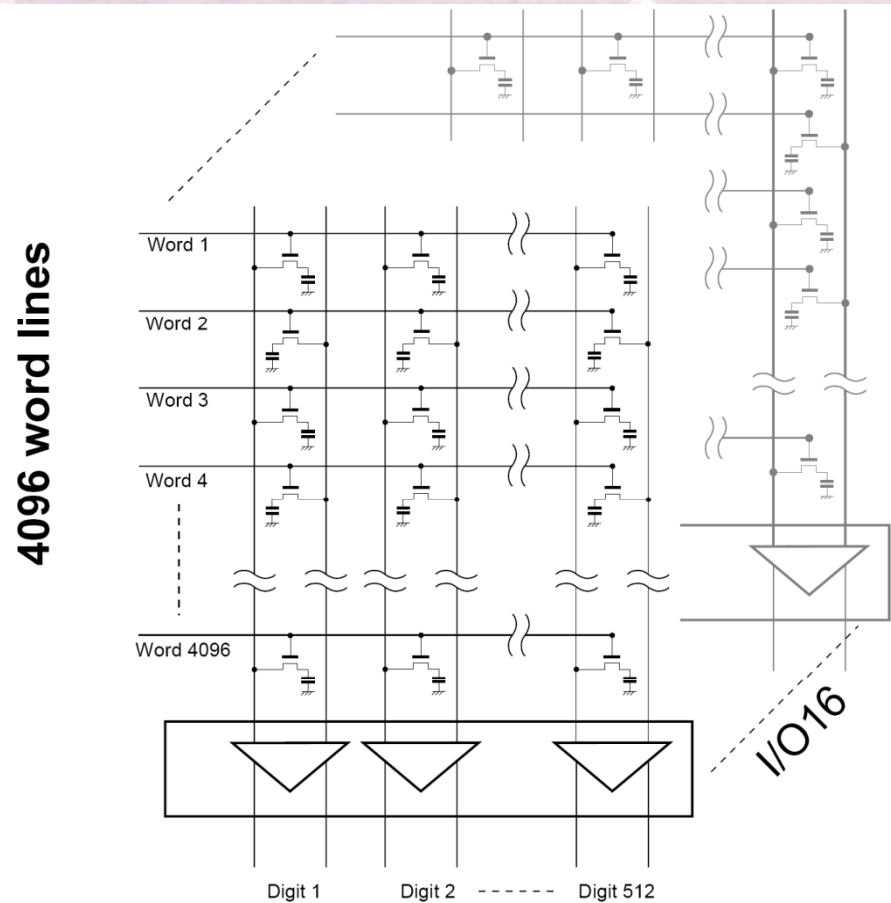


그림. Address Decoding

SDRAM의 내부 구조



512 digit lines

그림. Memory Cell Array



SDRAM의 초기화

Power-up sequence

1. Apply VDD and VDDQ at the same time. Keep CKE low during power up.
2. Wait for stable power.
3. Start clock and drive CKE high.

Caution Voltage on any input pin must not exceed $VDD+0.3V$ during power up.

Initialization sequence

4. After stable power and stable clock, wait $200\mu s$.
5. Issue precharge all command (PALL).
6. After tRP delay, issue 8 or more auto refresh commands (REF).
7. Set the mode register set command (MRS) to initialize the mode register.

Remark We recommend that you keep DQM and CKE high during initialization sequence to prevent data contention on the DQ bus.

그림. Memory Cell Array



SDRAM의 초기화

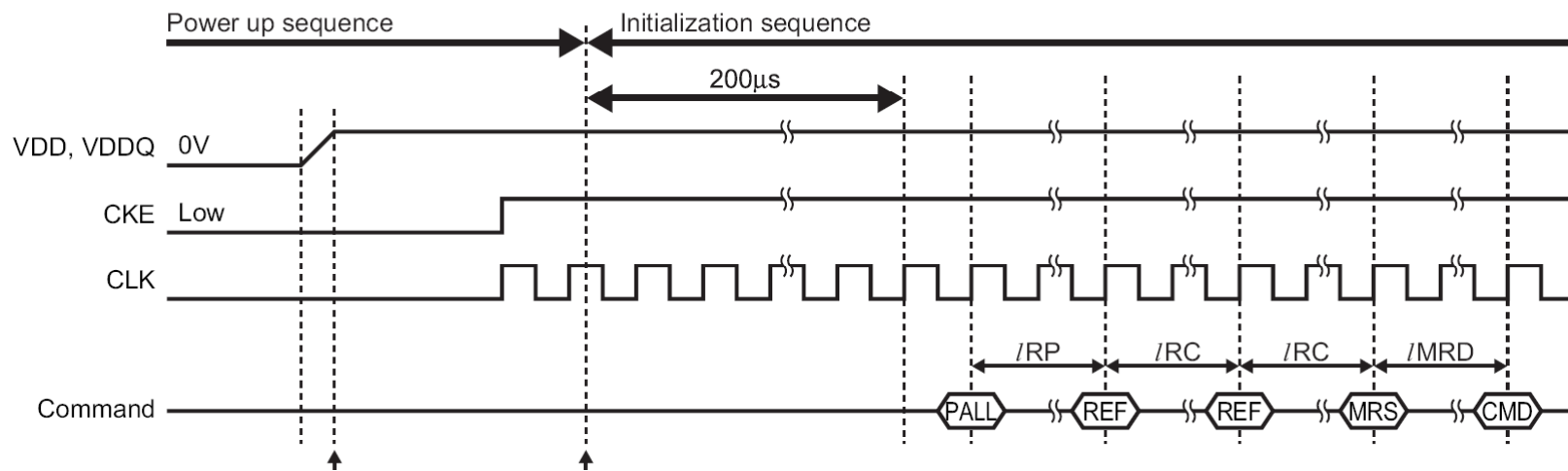


그림. Power up and Initialization Sequence

SDRAM의 초기화

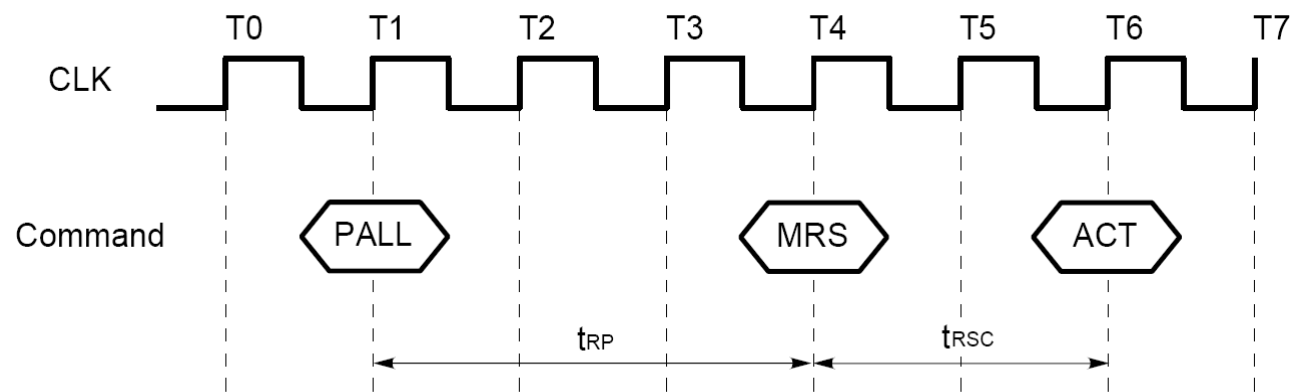


그림. Mode Register Setting Cycle

SDRAM의 초기화

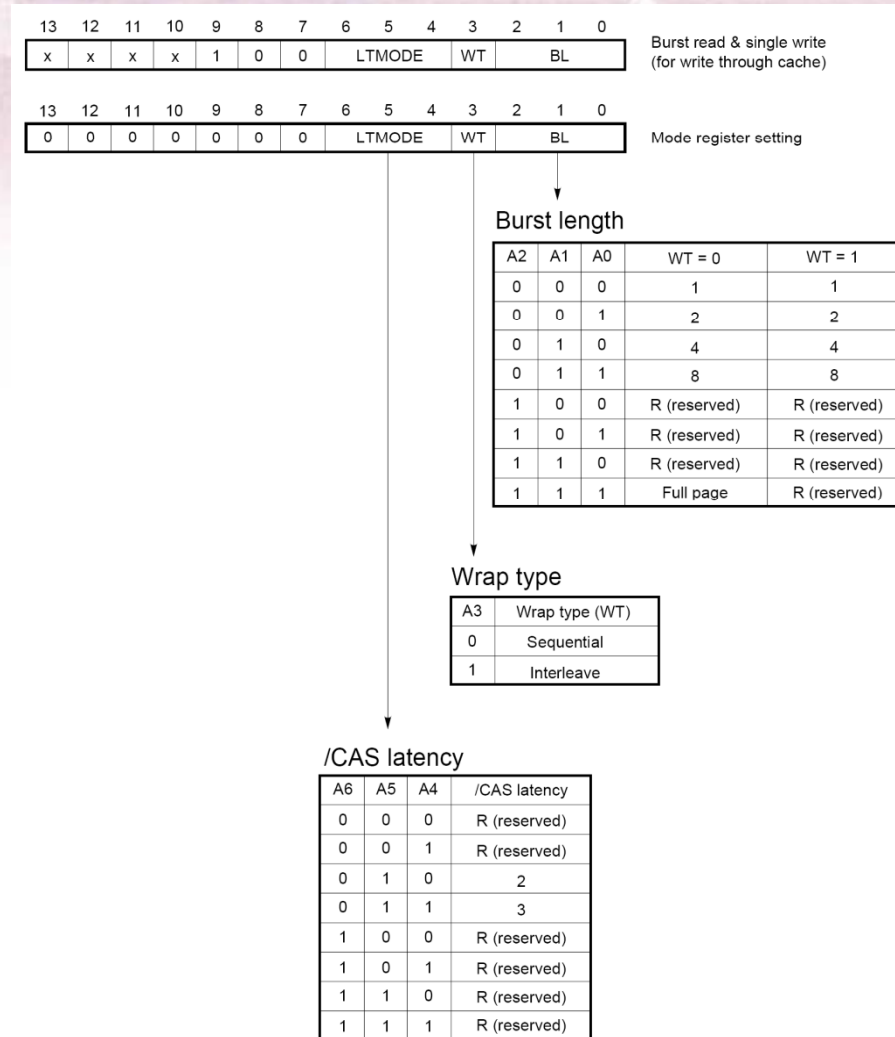


그림. Field of Mode Register (with 128M SDRAM)



레이턴시

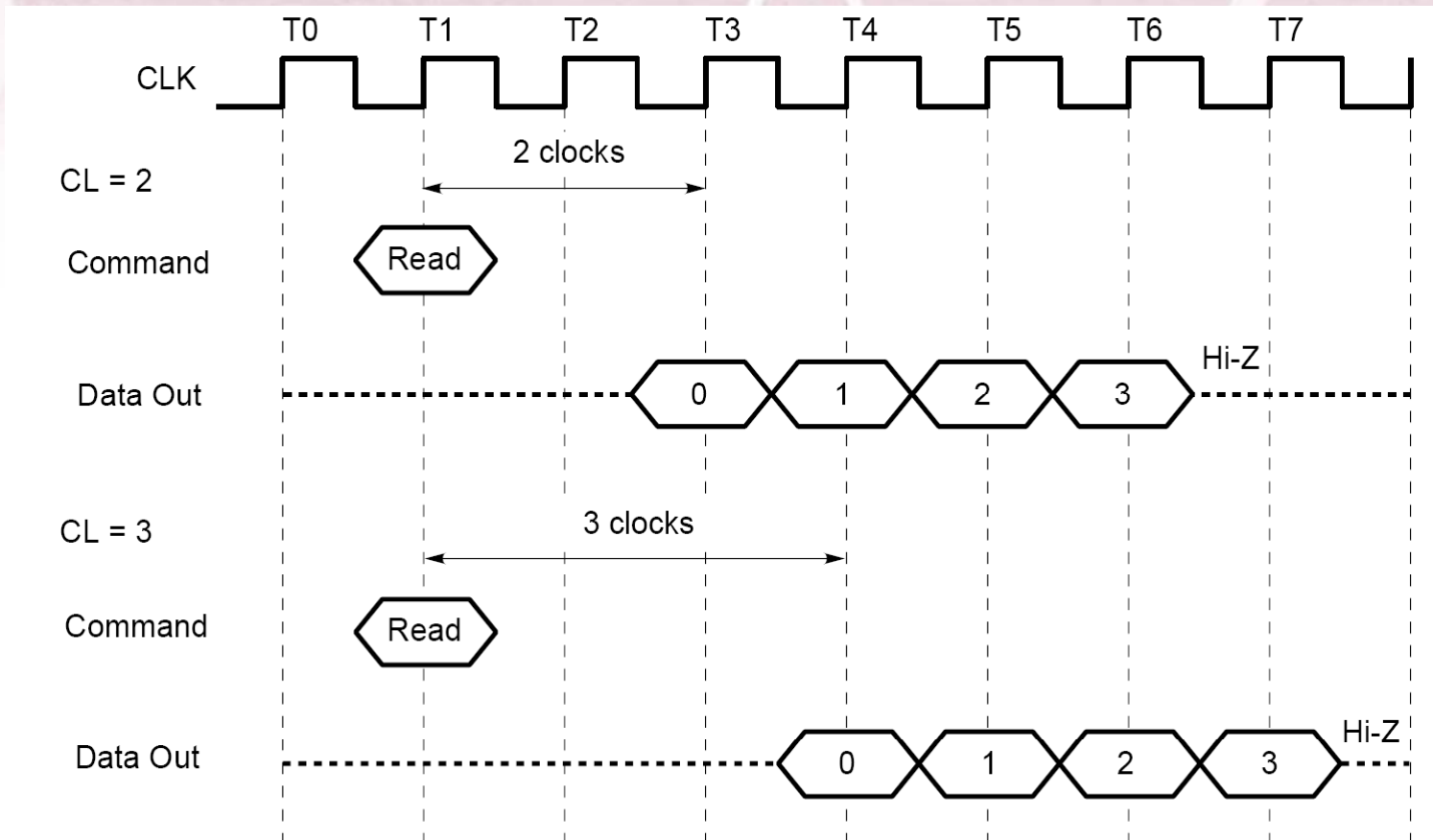


그림. Timing Differences between /CAS Latency = 2 and 3

BURST 오퍼레이션

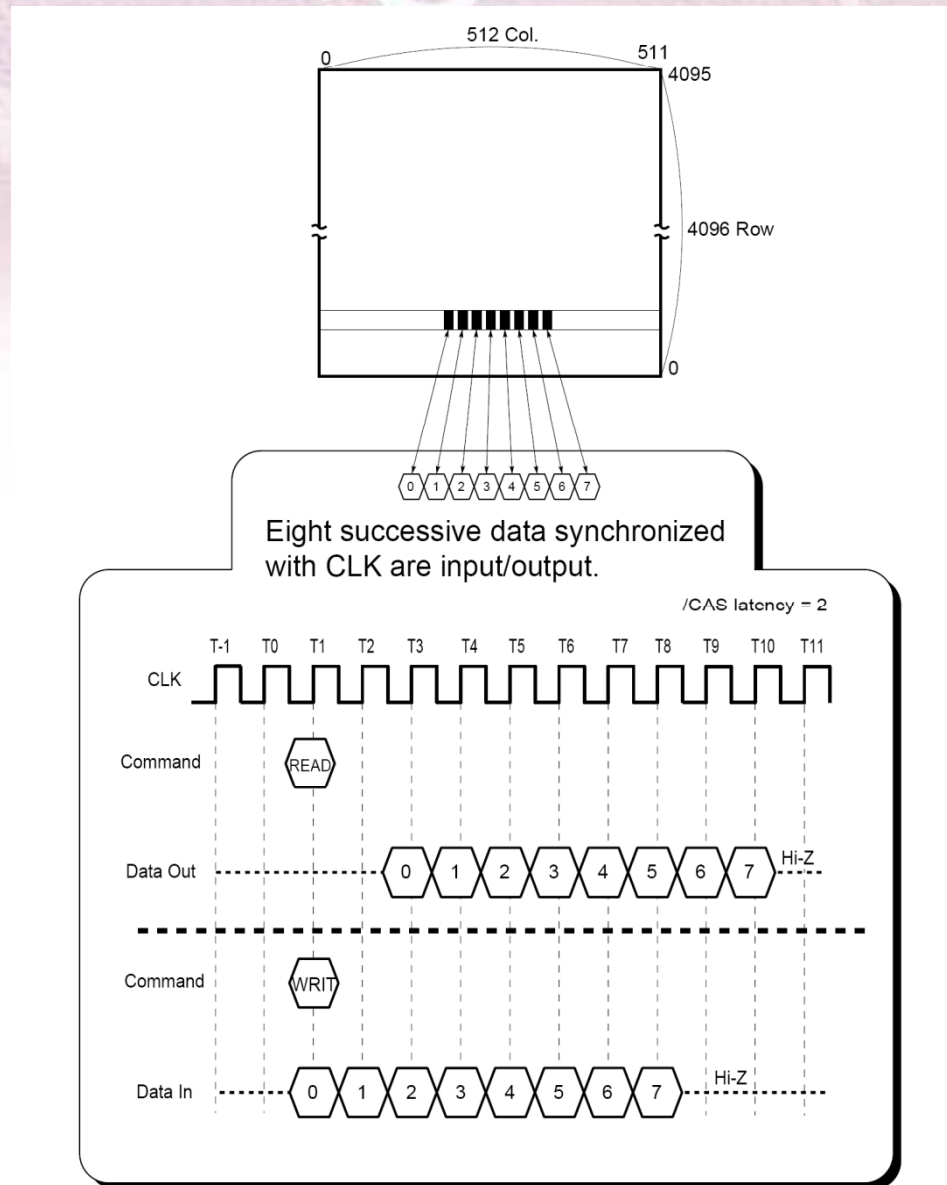


그림. Read/Write Cycle with Burst Length of 8

BURST 오퍼레이션

[Burst length = 2]

Start Address (column address A0, binary)	Sequential Addressing Sequence (decimal)	Interleave Addressing Sequence (decimal)
0	0, 1	0, 1
1	1, 0	1, 0

[Burst length = 4]

Start Address (column address A1 through A0, binary)	Sequential Addressing Sequence (decimal)	Interleave Addressing Sequence (decimal)
00	0, 1, 2, 3	0, 1, 2, 3
01	1, 2, 3, 0	1, 0, 3, 2
10	2, 3, 0, 1	2, 3, 0, 1
11	3, 0, 1, 2	3, 2, 1, 0

그림. Burst length and addressing sequence



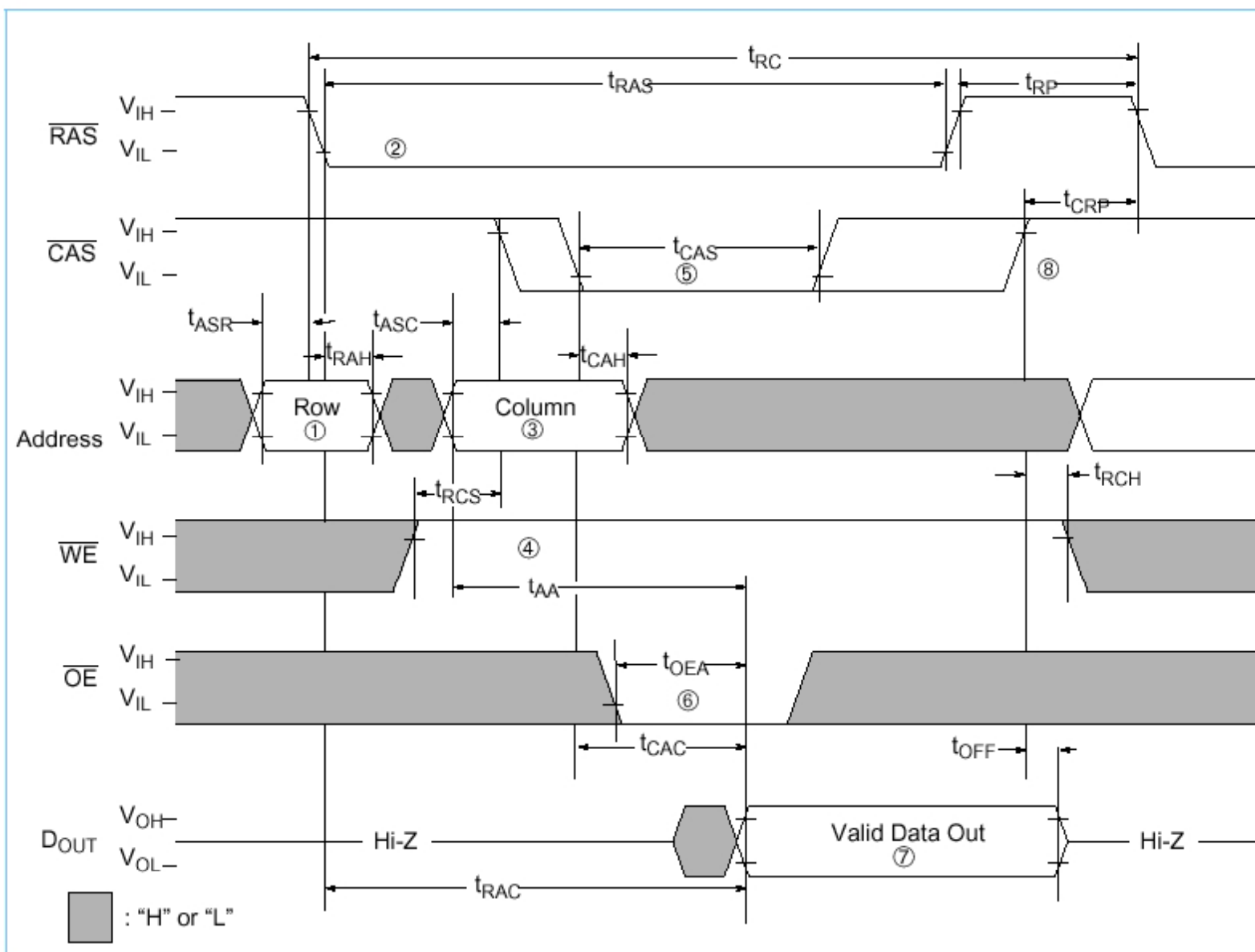
SDRAM 커맨드 일람

Command	Symbol	Command Executable (Input) Condition	Remark
Mode register set	MRS	All banks are in idle status.	
CBR (auto) refresh	REF	All banks are in idle status.	
Self refresh	SELF	All banks are in idle status.	
Precharge select bank	PRE	t_{RAS} after active command input (selected bank)	
Precharge all banks	PALL	t_{RAS} after active command input (all banks)	
Bank active	ACT	Selected bank is in idle status.	
Write	WRIT	t_{RCD} after active command input (selected bank)	
Write with auto precharge	WRITA	t_{RCD} after active command input (selected bank)	
Read	READ	t_{RCD} after active command input (selected bank)	
Read with auto precharge	READA	t_{RCD} after active command input (selected bank)	
Burst stop	BST	During read or write operation	
No operation	NOP	All status	
Device deselect	DESL	All status	

그림. Command Executable Condition



SDRAM 읽기 타이밍



SDRAM 읽기 타이밍

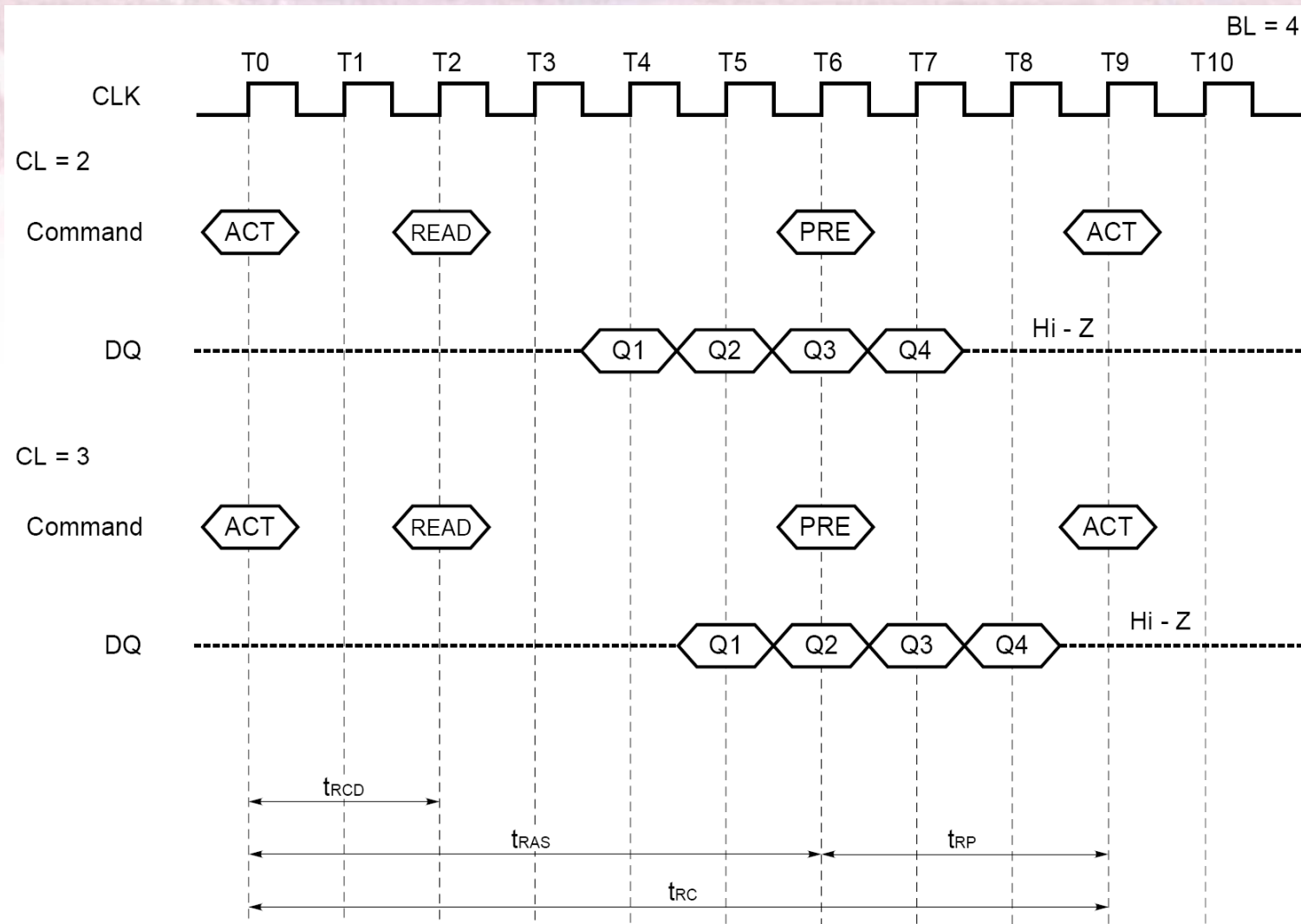


그림. Read Cycle

SDRAM 읽기 타이밍

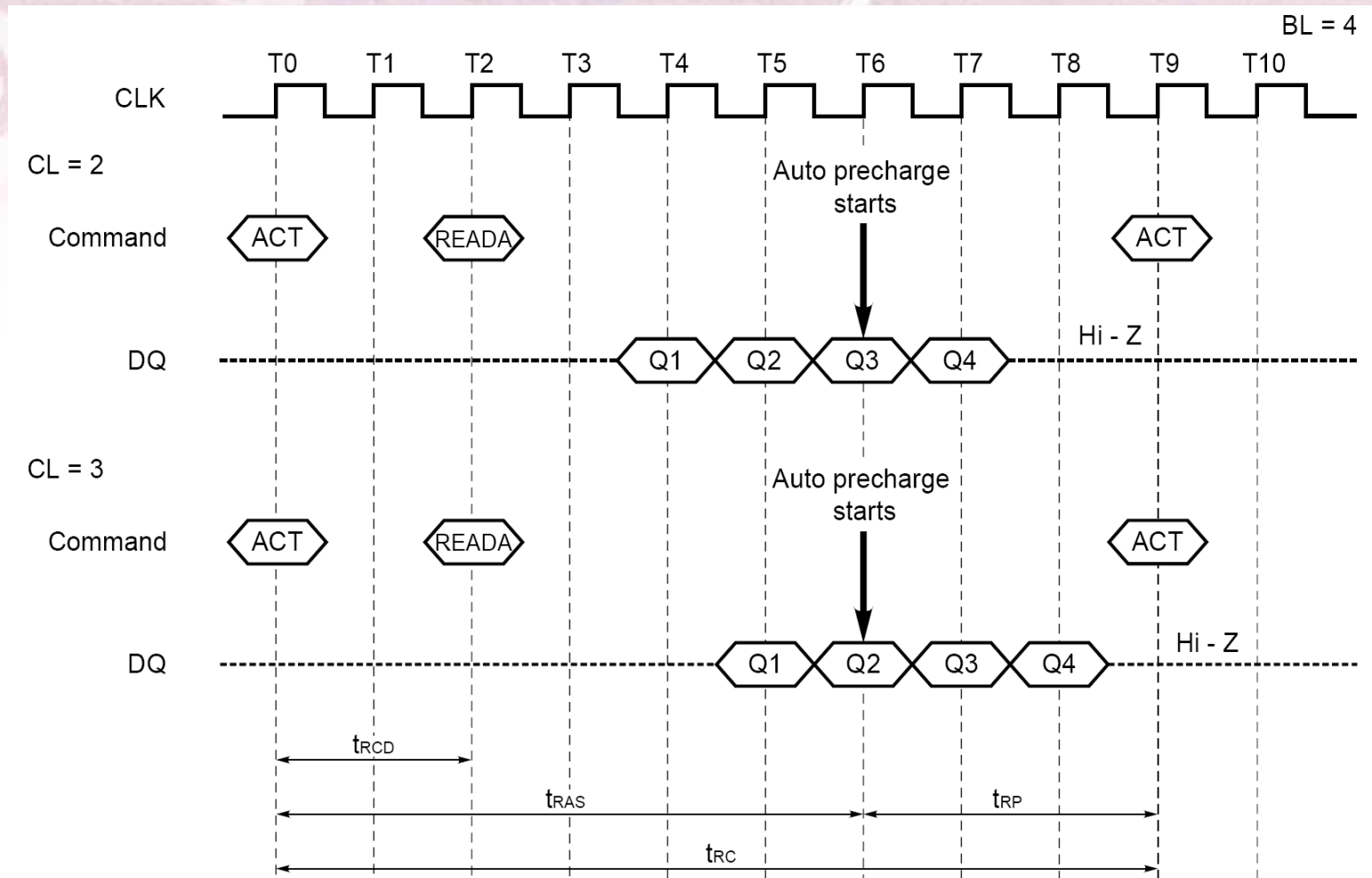
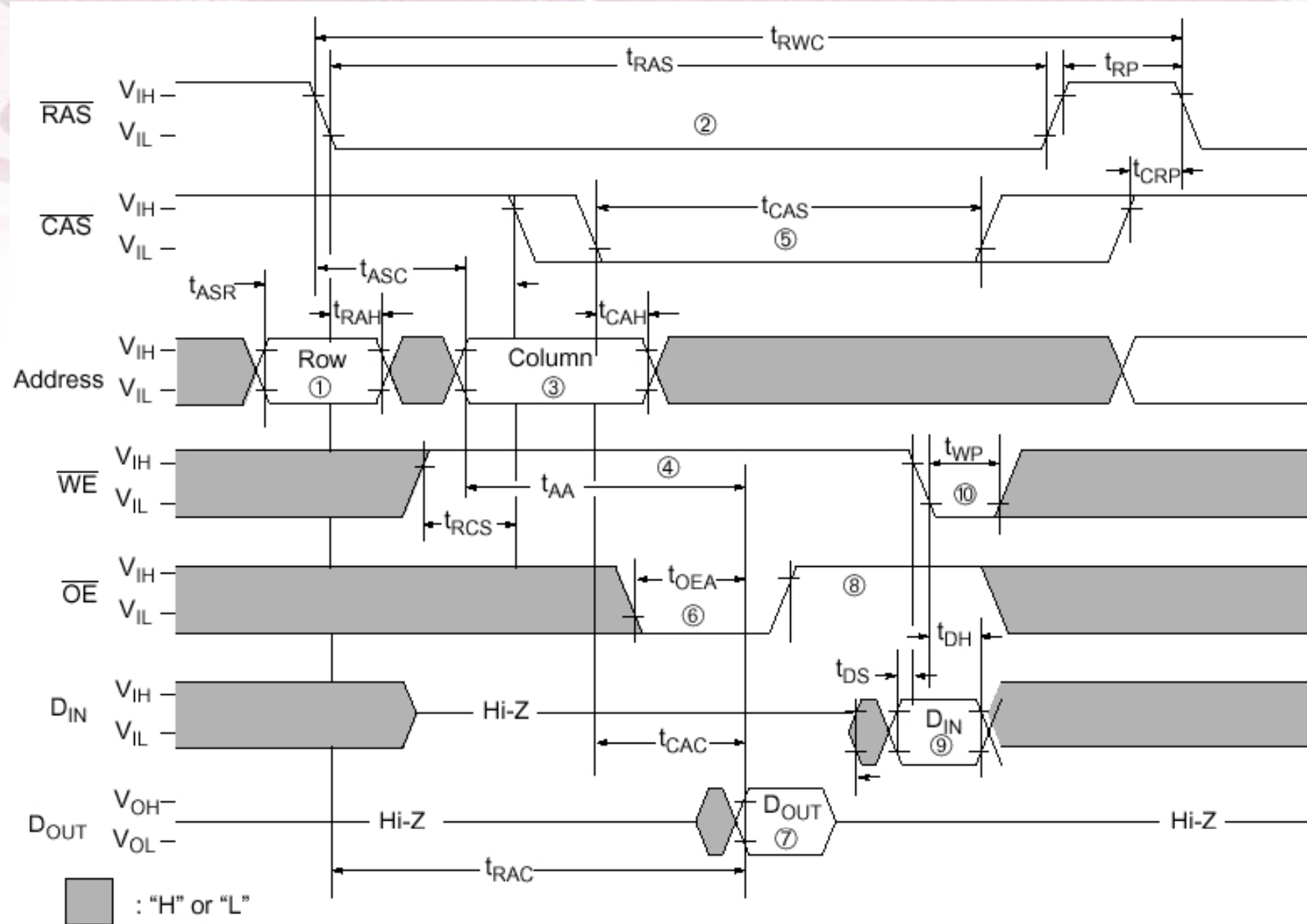


그림. Read Cycle with Auto Precharge

SDRAM 쓰기 타이밍



SDRAM 쓰기 타이밍

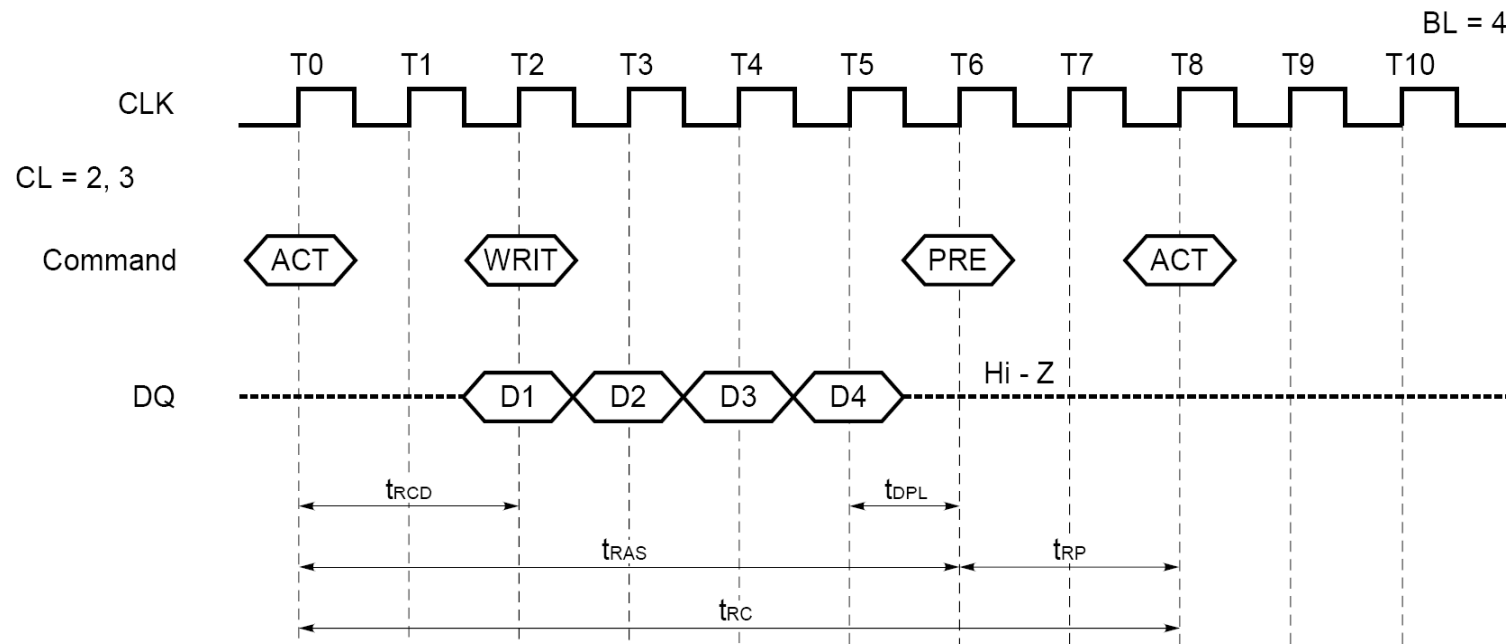


그림. Write Cycle

SDRAM 쓰기 타이밍

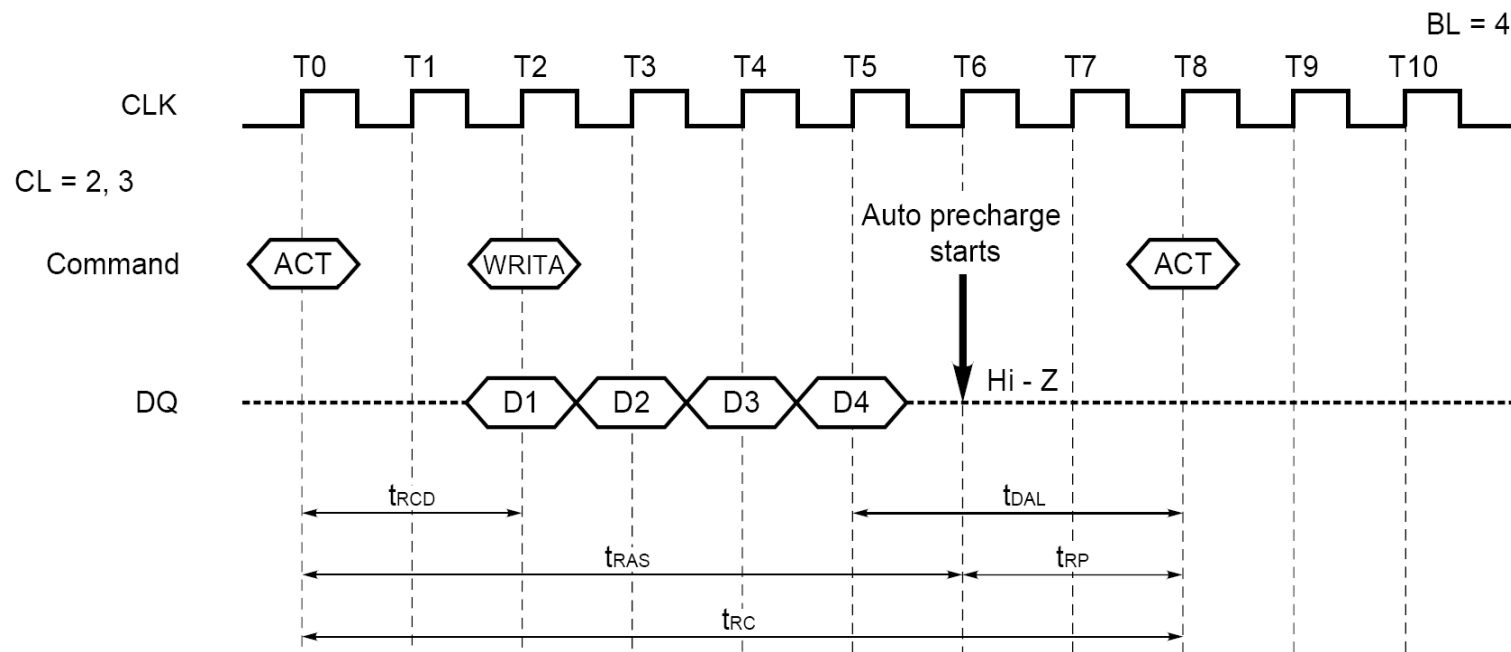


그림. Write Cycle with Auto Precharge

SDRAM 리플레쉬 타이밍

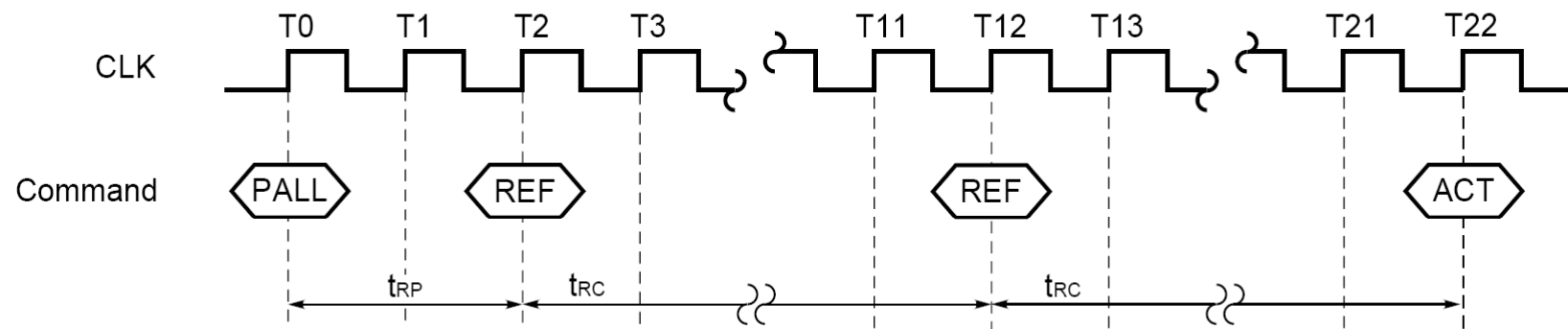


그림. CBR (Auto) Refresh Cycle

주요 신호 분석(DQM)

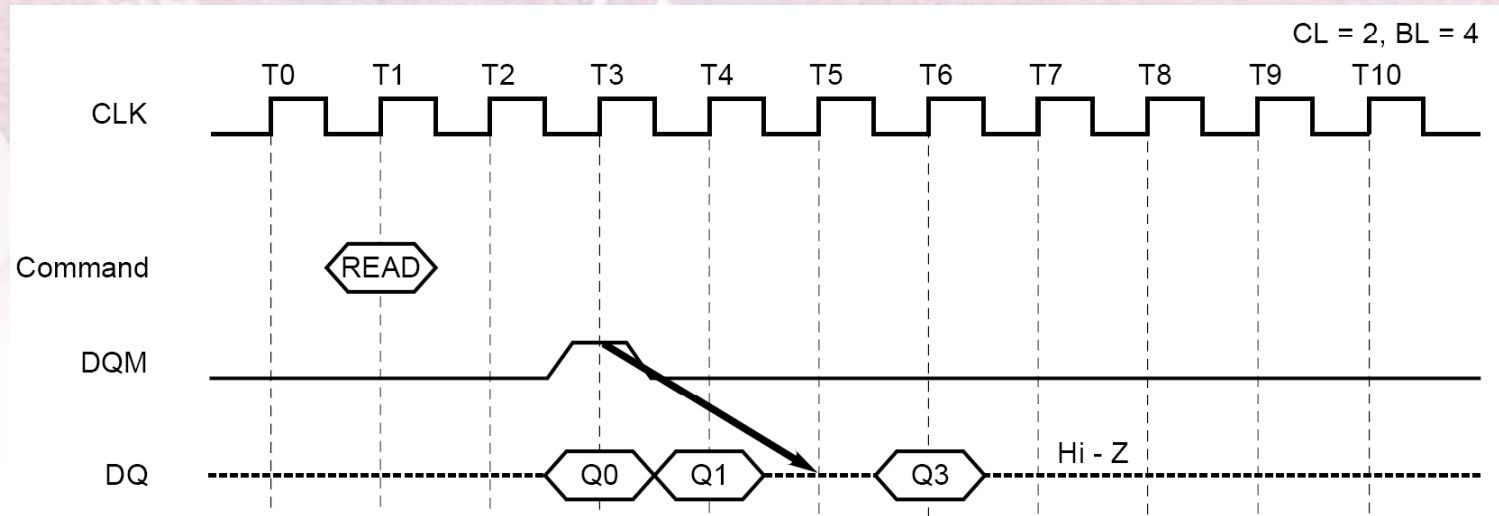


그림. DQM Control during Read Operation

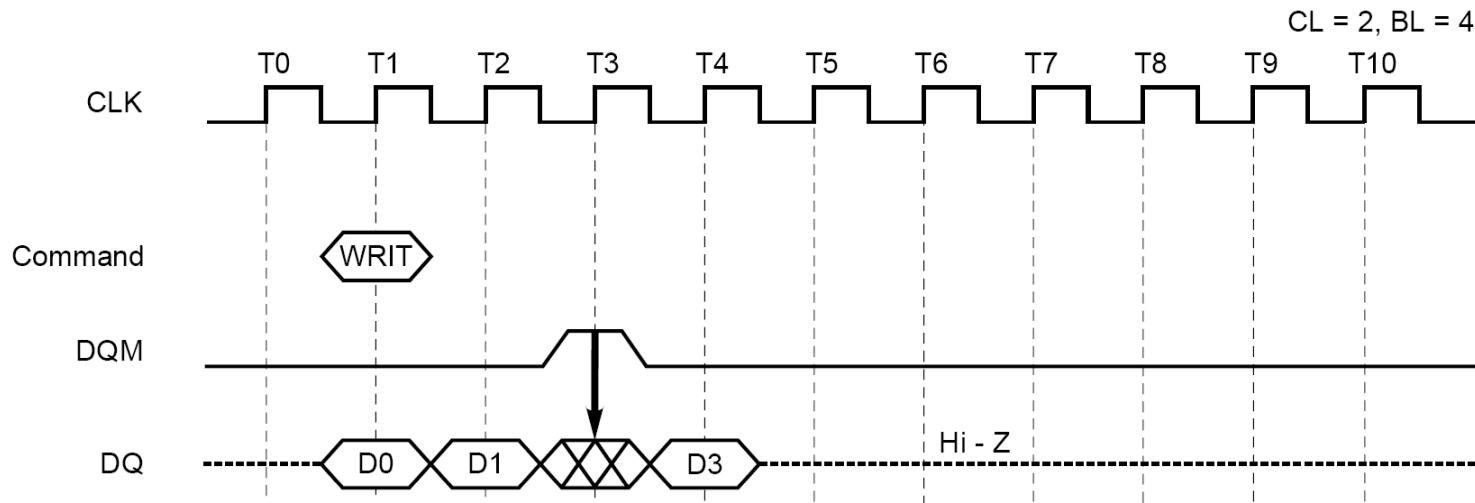


그림. DQM Control during Write Operation

주요 신호 분석(CKE)

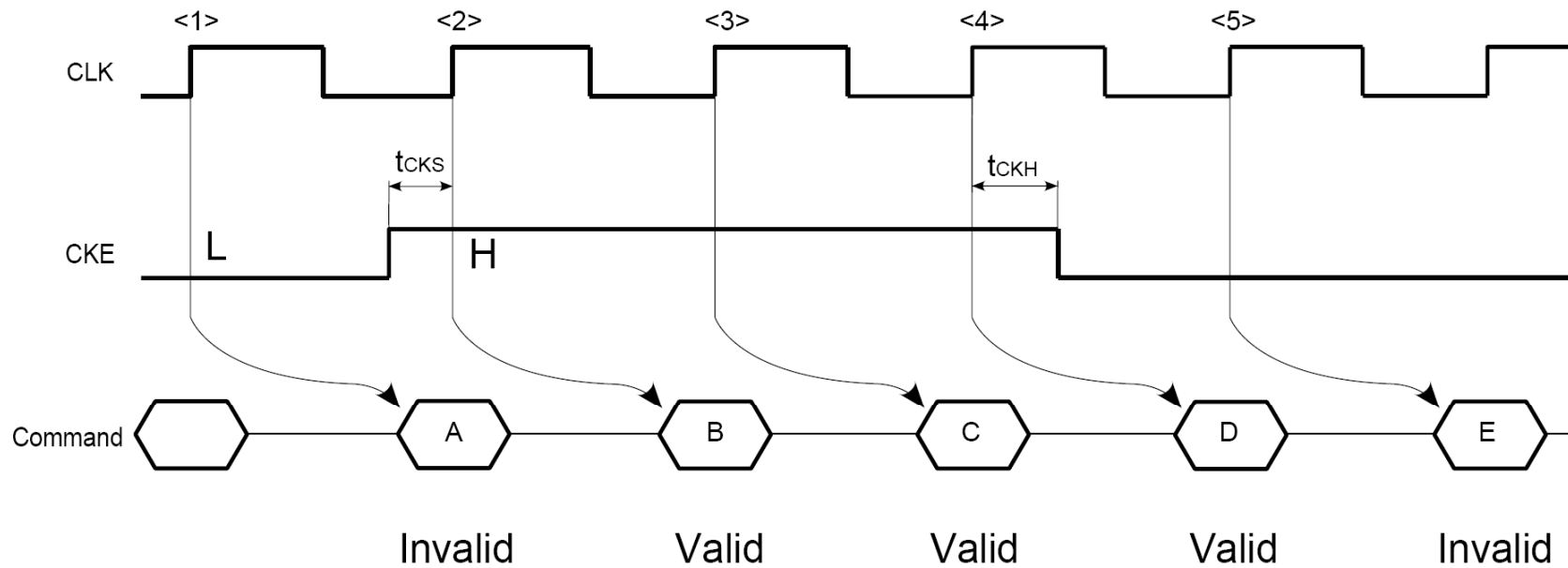
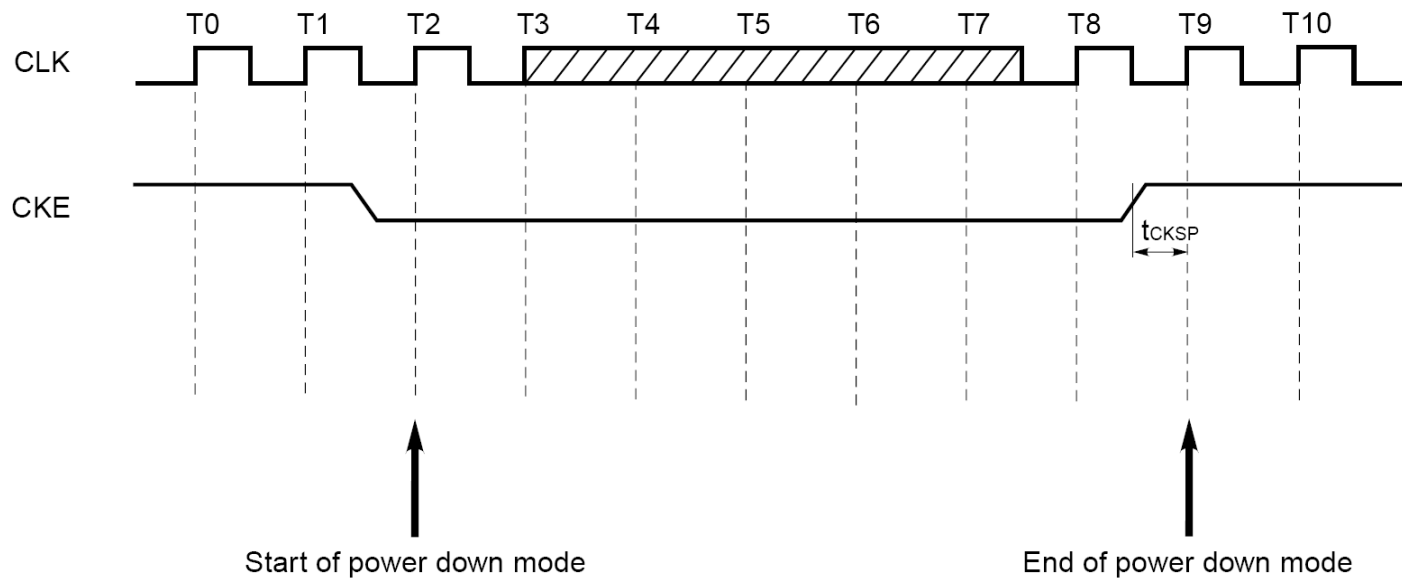


그림. Signal Input Timing Controlled by CKE

SDRAM 과 파워다운



- Remarks**
1. Commands cannot be input in the power down mode.
 2. Make sure that t_{REF} is satisfied.

그림. Power Down Mode



SDRAM 과 파워다운

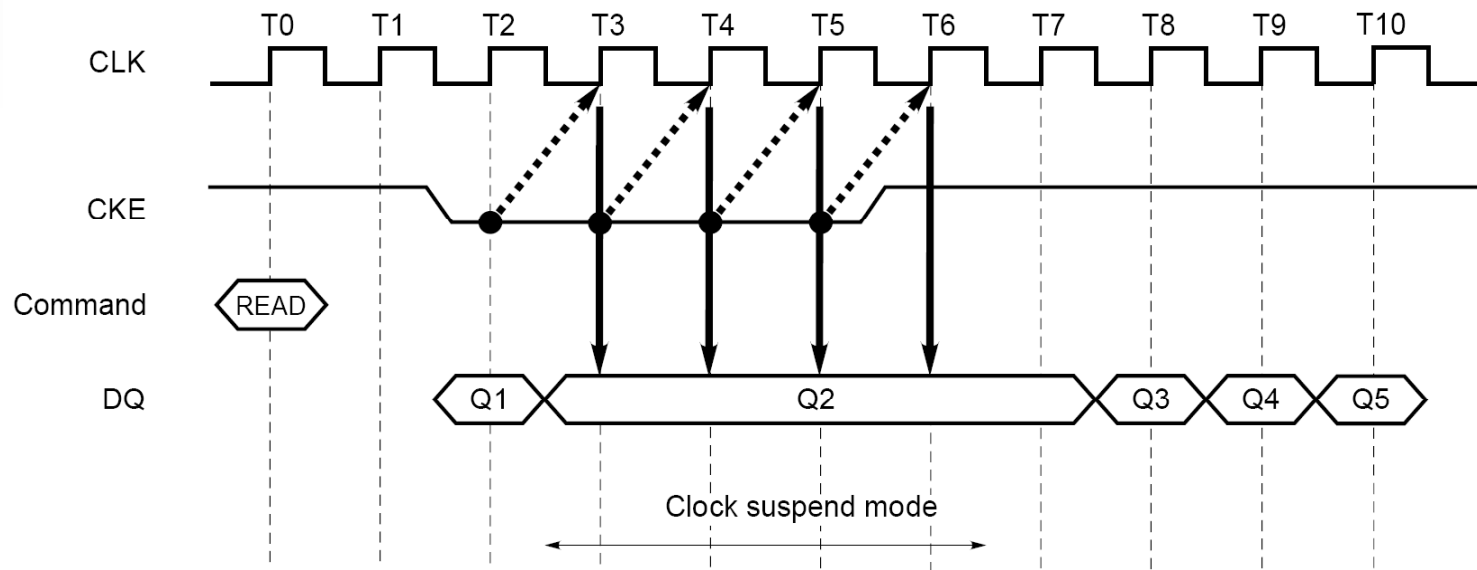


그림. Clock Suspend Mode (read cycle: CL = 2)

SDRAM 과 파워다운

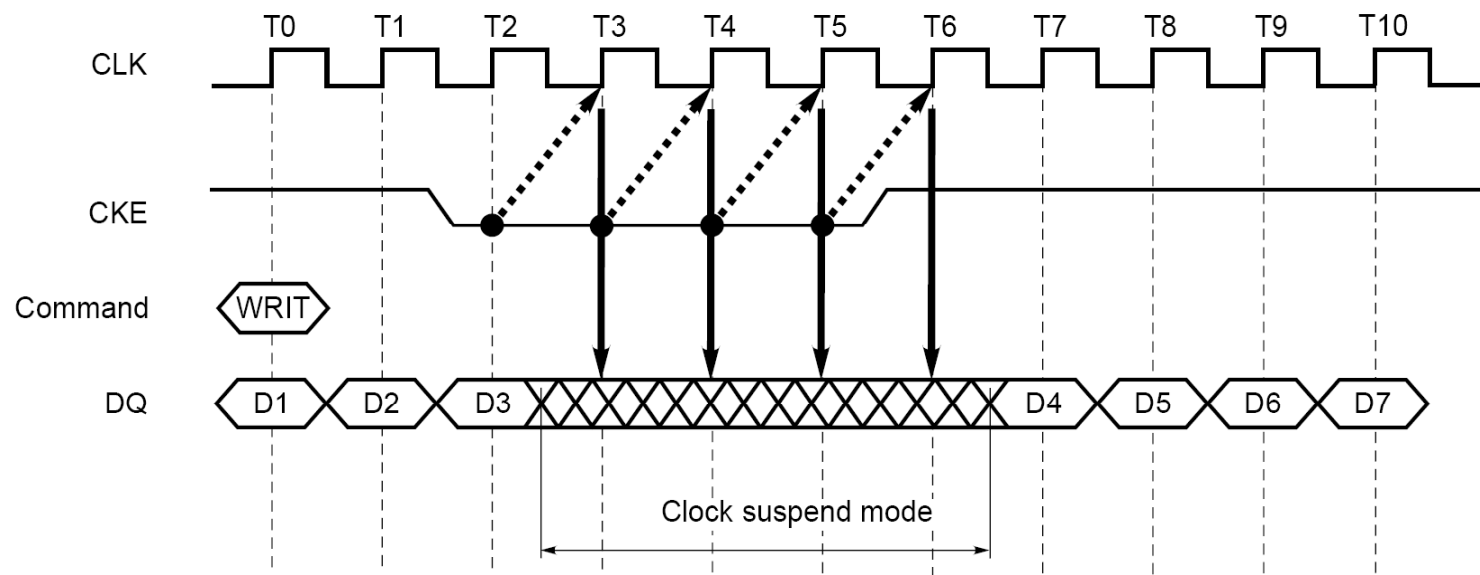
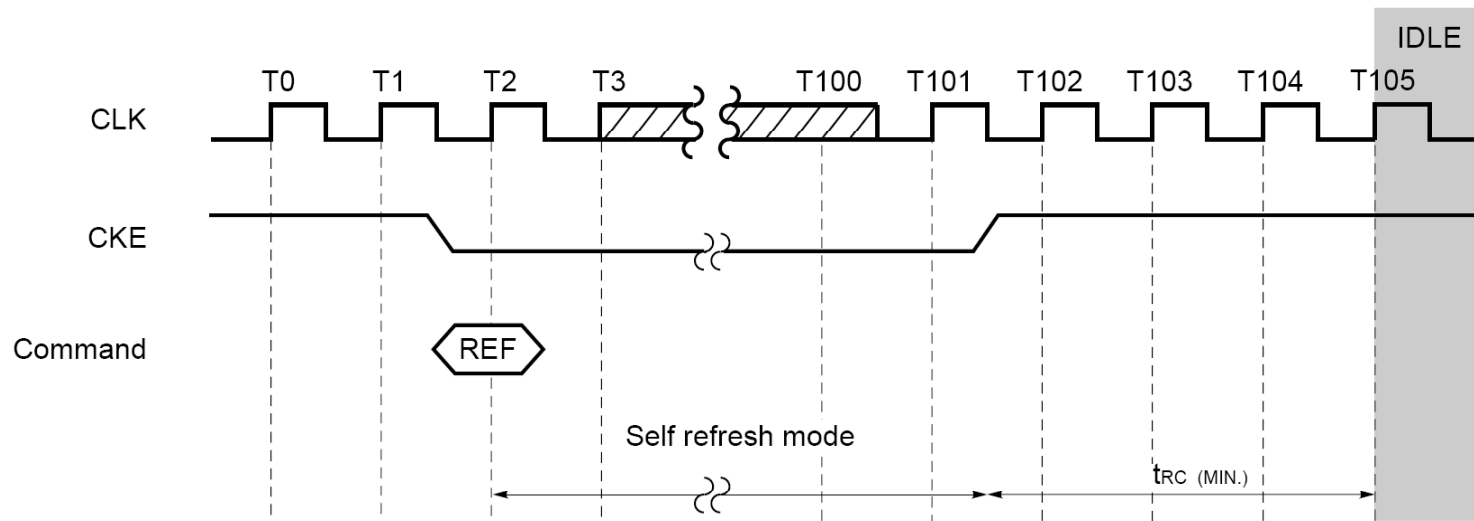


그림. Clock Suspend Mode (write cycle)

SDRAM 과 파워다운

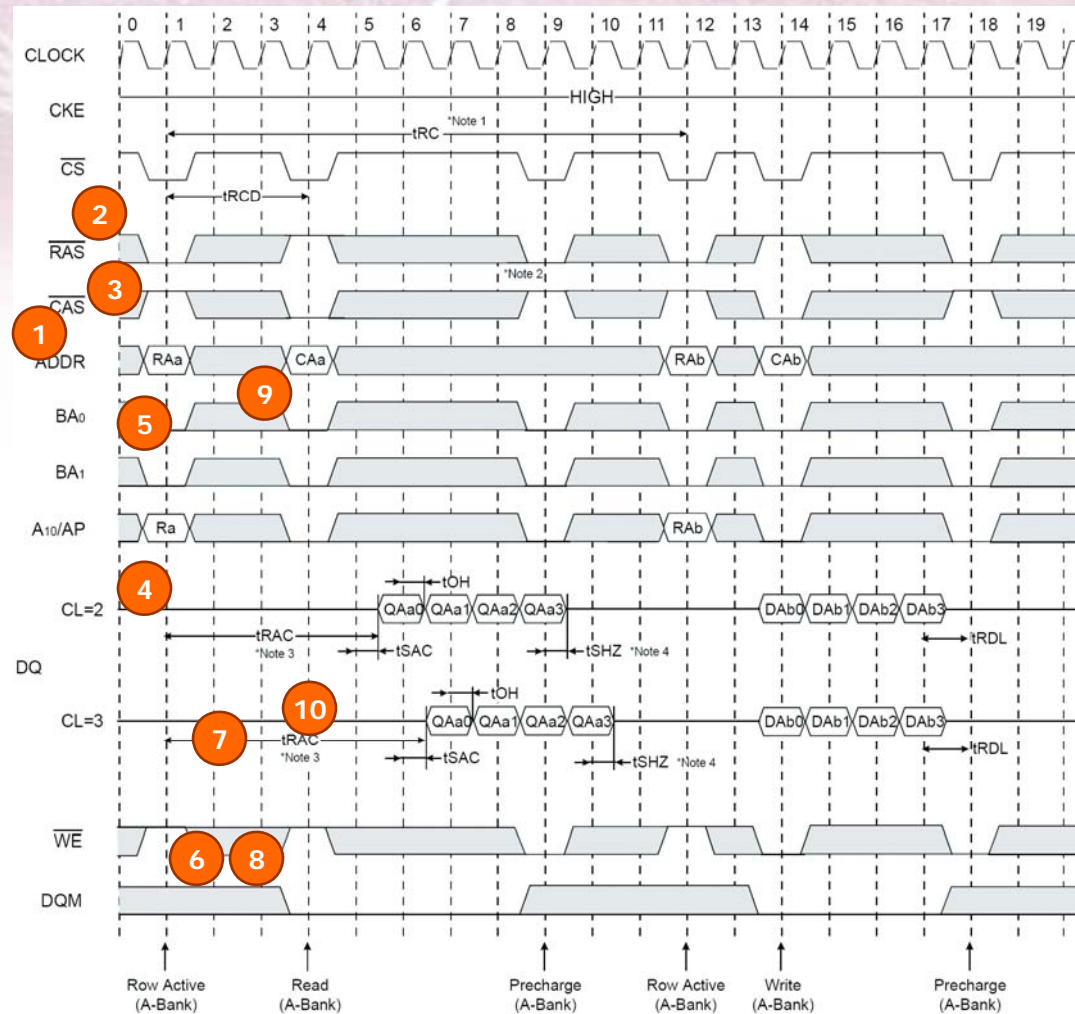


Caution When using concentrated refresh during normal operation, CBR refresh (auto refresh) must be concentrated and executed for the duration of the total number of refresh cycles before and after the self refresh operation.

그림. Self Refresh Mode



총정리



□ : Don't care

그림. SAMSUNG DATASHEET

